FAIRCHILD SEMICONDUCTOR™

January 1988
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MM74HC597
8-Bit Shift Registers with Input Latches

General Description

This high speed register utilizes advanced silicon-gate CMOS technology. It has the high noise immunity and low power consumption of standard CMOS integrated circuits, as well as the ability to drive 10 LS-TTL loads.

The MM74HC597 comes in a 16-pin package and consists of an 8-bit storage latch feeding a parallel-in, serial-out 8-bit shift register. Both the storage register and shift register have positive-edge triggered clocks. the shift register also has direct load (from storage) and clear inputs.

The 74HC logic family is speed, function, and pin-out compatible with the standard 74LS logic family. All inputs are protected from damage due to static discharge by internal diode clamps to V_{CC} and ground.

Features

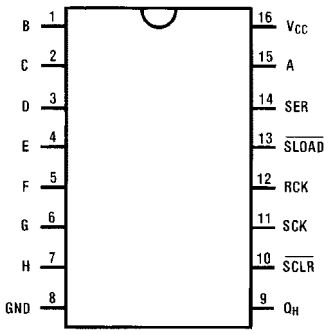
- 8-bit parallel storage register inputs
- Wide operating voltage range: 2V–6V
- Shift register has direct overriding load and clear
- Guaranteed shift frequency: DC to 30 MHz
- Low quiescent current: 80 μA maximum

Ordering Code:

Order Number	Package Number	Package Description
MM74HC597M (Note 1)	M16A	16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
MM74HC597SJ	M16D	16-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
MM74HC597N	N16E	16-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

Note 1: Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Connection Diagram

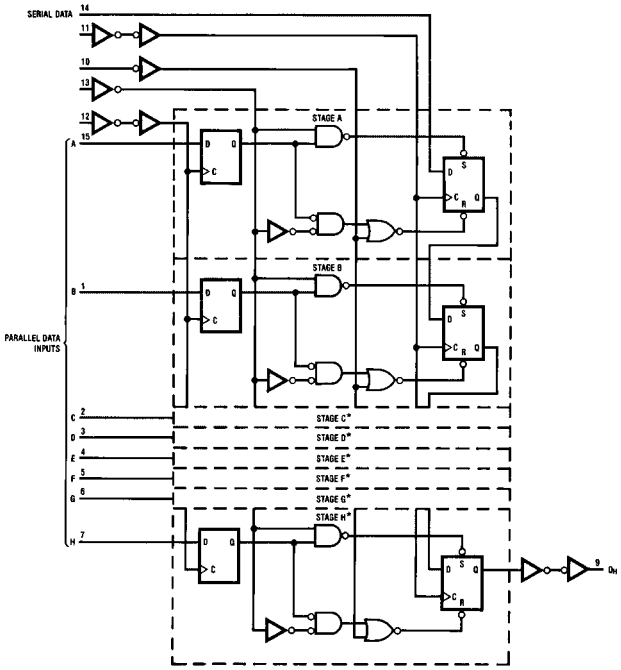


Top View

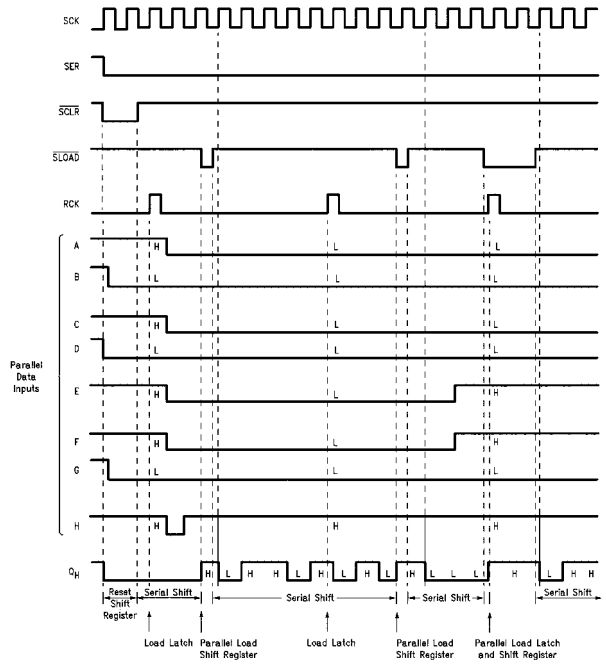
Truth Table

RCK	SCK	$\overline{SLOAD}$	$\overline{SCLR}$	Function
↑	X	X	X	Data Loaded to input latches
↑	X	L	H	Data loaded from inputs to shift register
No clock edge	X	L	H	Data transferred from input latches to shift register
X	X	L	L	Invalid logic, state of shift register indeterminate when signals removed
X	X	H	L	Shift register cleared
X	↑	H	H	Shift register clocked $Q_n = Q_n–1$, Q_0 = SER

Functional Block Diagram (Positive Logic)



Timing Diagram



Absolute Maximum Ratings(Note 2)

(Note 3)

Supply Voltage (V_{CC})	−0.5 to +7.0V
DC Input Voltage (V_{IN})	−1.5 to V_{CC}+1.5V
DC Output Voltage (V_{OUT})	−0.5 to V_{CC}+0.5V
Clamp Diode Current (I_{IK}, I_{OK})	±20 mA
DC Output Current, per pin (I_{OUT})	±25 mA
DC V_{CC} or GND Current, per pin (I_{CC})	±70 mA
Storage Temperature Range (T_{STG})	−65°C to +150°C
Power Dissipation (P_D)	
(Note 4)	600 mW
S.O. Package only	500 mW
Lead Temperature (T_L)	
(Soldering 10 seconds)	260°C

Recommended Operating Conditions

	Min	Max	Units
Supply Voltage (V_{CC})	2	6	V
DC Input or Output Voltage			
(V_{IN}, V_{OUT})	0	V_{CC}	V
Operating Temperature Range (T_A)	−40	+85	°C
Input Rise or Fall Times			
(t_r, t_f) V_{CC} = 2.0V		1000	ns
V_{CC} = 4.5V		500	ns
V_{CC} = 6.0V		400	ns

Note 2: Absolute Maximum Ratings are those values beyond which damage to the device may occur.

Note 3: Unless otherwise specified all voltages are referenced to ground.

Note 4: Power Dissipation temperature derating — plastic "N" package: −12 mW/°C from 65°C to 85°C.

DC Electrical Characteristics (Note 5)

Symbol	Parameter	Conditions	V_{CC}	T_A = 25°C	T_A = −40 to 85°C	T_A = −55 to 125°C	Units
				Typ	Guaranteed Limits		
V_{IH}	Minimum HIGH Level Input Voltage		2.0V		1.5	1.5	1.5	V
			4.5V		3.15	3.15	3.15	
			6.0V		4.2	4.2	4.2	
V_{IL}	Maximum LOW Level Input Voltage (Note 6)		2.0V		0.5	0.5	0.5	V
			4.5V		1.35	1.35	1.35	
			6.0V		1.8	1.8	1.8	
V_{OH}	Minimum HIGH Level Output Voltage	V_{IN} = V_{IH} or V_{IL} $\|I_{OUT}\| \leq 20$ μA	2.0V	2.0	1.9	1.9	1.9	V
			4.5V	4.5	4.4	4.4	4.4	
			6.0V	6.0	5.9	5.9	5.9	
		V_{IN} = V_{IH} or V_{IL} $\|I_{OUT}\| \leq 4.0$ mA	4.5V	4.2	3.98	3.84	3.7	V
		$\|I_{OUT}\| \leq 5.2$ mA	6.0V	5.2	5.48	5.34	5.2	
V_{OL}	Maximum LOW Level Output Voltage	V_{IN} = V_{IH} or V_{IL} $\|I_{OUT}\| \leq 20$ μA	2.0V	0	0.1	0.1	0.1	V
			4.5V	0	0.1	0.1	0.1	
			6.0V	0	0.1	0.1	0.1	
		V_{IN} = V_{IH} or V_{IL} $\|I_{OUT}\| \leq 4$ mA	4.5V	0.2	0.26	0.33	0.4	V
		$\|I_{OUT}\| \leq 5.2$ mA	6.0V	0.2	0.26	0.33	0.4	
I_{IN}	Maximum Input Current	V_{IN} = V_{CC} or GND	6.0V		±0.1	±1.0	±1.0	μA
I_{CC}	Maximum Quiescent Supply Current	V_{IN} = V_{CC} or GND I_{OUT} = 0 μA	6.0V		8.0	80	160	μA

Note 5: For a power supply of 5V ± 10% the worst case output voltages (V_{OH}, and V_{OL}) occur for HC at 4.5V. Thus the 4.5V values should be used when designing with this supply. Worst case V_{IH} and V_{IL} occur at V_{CC} = 5.5V and 4.5V respectively. (The V_{IH} value at 5.5V is 3.85V.) The worst case leakage current (I_{IN}, I_{CC}, and I_{OZ}) occur for CMOS at the higher voltage and so the 6.0V values should be used.

Note 6: V_{IL} limits are currently tested at 20% of V_{CC}. The above V_{IL} specification (30% of V_{CC}) will be implemented no later than Q1, CY'89.

AC Electrical Characteristics V_{CC} = 5V, T_A = 25°C, C_L = 15 pF, $t_r = t_f$ = 6 ns

Symbol	Parameter	Conditions	Typ	Guaranteed Limit	Units
f_{MAX}	Maximum Operating Frequency of SCK		50	30	MHz
t_{PHL} t_{PLH}	Maximum Propagation Delay from SCK to Q_H		20	30	ns
t_{PHL} t_{PLH}	Maximum Propagation Delay from $\overline{SLOAD}$ to Q_H		20	30	ns
t_{PHL} t_{PLH}	Maximum propagation Delay from RCK to Q_H	$\overline{SLOAD}$ = logic "0"	25	45	ns
t_{PHL}	Maximum Propagation Delay from $\overline{SCLR}$ to Q_H		20	30	ns
t_{REM}	Minimum Removal Time, $\overline{SCLR}$ to SCK		10	20	ns
t_S	Minimum Setup Time from RCK to SCK		30	40	ns
t_S	Minimum Setup Time from SER to SCK		10	20	ns
t_S	Minimum Setup Time from inputs A thru H to RCK		10	20	ns
t_H	Minimum Hold Time		–2	0	ns
t_W	Minimum Pulse Width SCK, RCK, $\overline{SCLR}$ $\overline{SLOAD}$		10	16	ns

AC Electrical Characteristics V_{CC} = 2.0–6.0V, C_L = 50 pF, $t_r = t_f$ = 6 ns (unless otherwise specified)

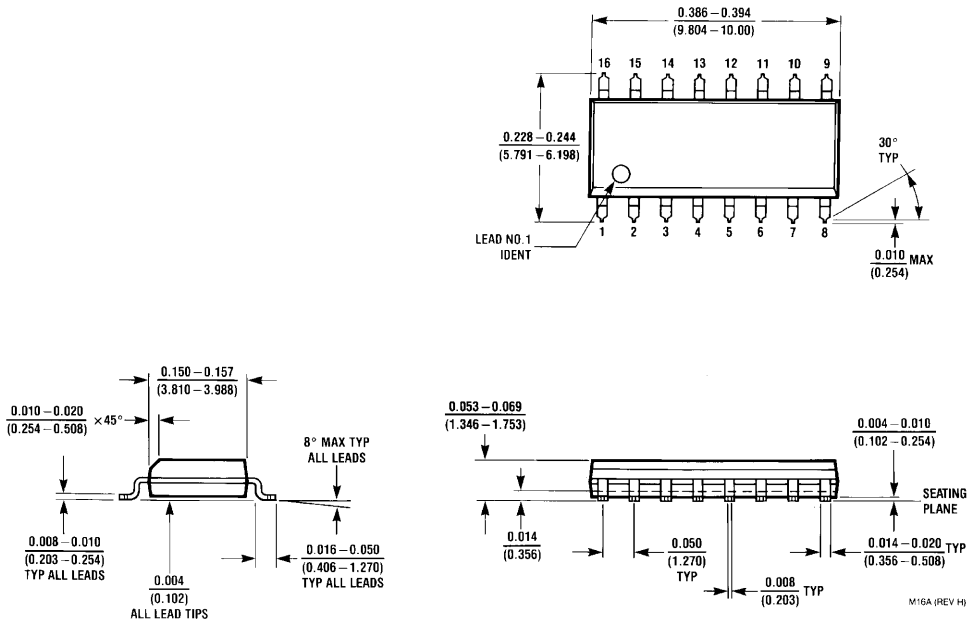
Symbol	Parameter	Conditions	V_{CC}	T_A = 25°C	T_A=–40 to 85°C	T_A=–55 to 125°C	Units
				Typ	Guaranteed Limits		
f_{MAX}	Maximum Operating Frequency		2.0V	10	6.0	4.8	4.0	MHz
			4.5V	45	30	24	20	
			6.0V	50	35	28	24	
t_{PHL} t_{PLH}	Maximum Propagation Delay from SCK to Q_H		2.0V	62	175	220	263	ns
			4.5V	20	35	44	53	
			6.0V	18	30	38	45	
t_{PHL} t_{PLH}	Maximum Propagation Delay from $\overline{SLOAD}$ to Q_H		2.0V	65	175	220	263	ns
			4.5V	20	35	44	53	
			6.0V	18	30	38	45	
t_{PHL} t_{PLH}	Maximum Propagation Delay from RCK to Q_H	SLOAD = Logic "0"	2.0V	120	205	255	310	ns
			4.5V	30	41	51	62	
			6.0V	28	35	43	53	
t_{PHL}	Maximum Propagatin Delay from $\overline{SCLR}$ to Q_H		2.0V	66	175	220	263	ns
			4.5V	20	35	44	53	
			6.0V	18	30	38	45	
t_{REM}	Minimum Removal Time $\overline{SCLR}$ to SCK		2.0V		100	125	150	ns
			4.5V		20	25	30	
			6.0V		17	21	25	
t_S	Minimum Setup Time from RCK to SCK		2.0V		200	250	300	ns
			4.5V		40	50	60	
			6.0V		34	42	50	
t_S	Minimum Setup Time from SER to SCK		2.0V		100	125	150	ns
			4.5V		20	25	30	
			6.0V		17	21	25	

AC Electrical Characteristics (Continued)

Symbol	Parameter	Conditions	V_{CC}	T_A = 25°C	T_A=−40 to 85°C	T_A=−55 to 125°C	Units
				Typ	Guaranteed Limits		
t_S	Minimum Setup Time		2.0V		100	125	150	
	from Inputs A thru H		4.5V		20	25	30	ns
	to RCK		6.0V		17	21	25	
t_H	Minimum Hold Time		2.0V		0	0	0	
			4.5V		0	0	0	ns
			6.0V		0	0	0	
t_W	Minimum Pulse Width		2.0V	30	80	100	120	
	SCK, RCK, $\overline{SCLR}$, $\overline{SLOAD}$		4.5V	9	16	20	24	ns
			6.0V	8	14	18	20	
t_r, t_f	Maximum Input Rise and		2.0V		1000	1000	1000	
	Fall Time		4.5V		500	500	500	ns
			6.0V		400	400	400	
t_{THL}, t_{TLH}	Maximum Output		2.0V	30	75	95	110	
	Rise and Fall Time		4.5V	10	15	19	22	ns
			6.0V	8	13	16	19	
t_{THL}, t_{TLH}	Maximum Output		2.0V		75	95	110	
	Rise and Fall Time		4.5V		15	19	22	ns
			6.0V		13	16	19	
C_{PD}	Power Dissipation			87				pF
	Capacitance, Outputs (Note 7)							
C_{IN}	Maximum Input			5	10	10	10	pF
	Capacitance							
C_{OUT}	Maximum Output			15	20	20	20	pF
	Capacitance							

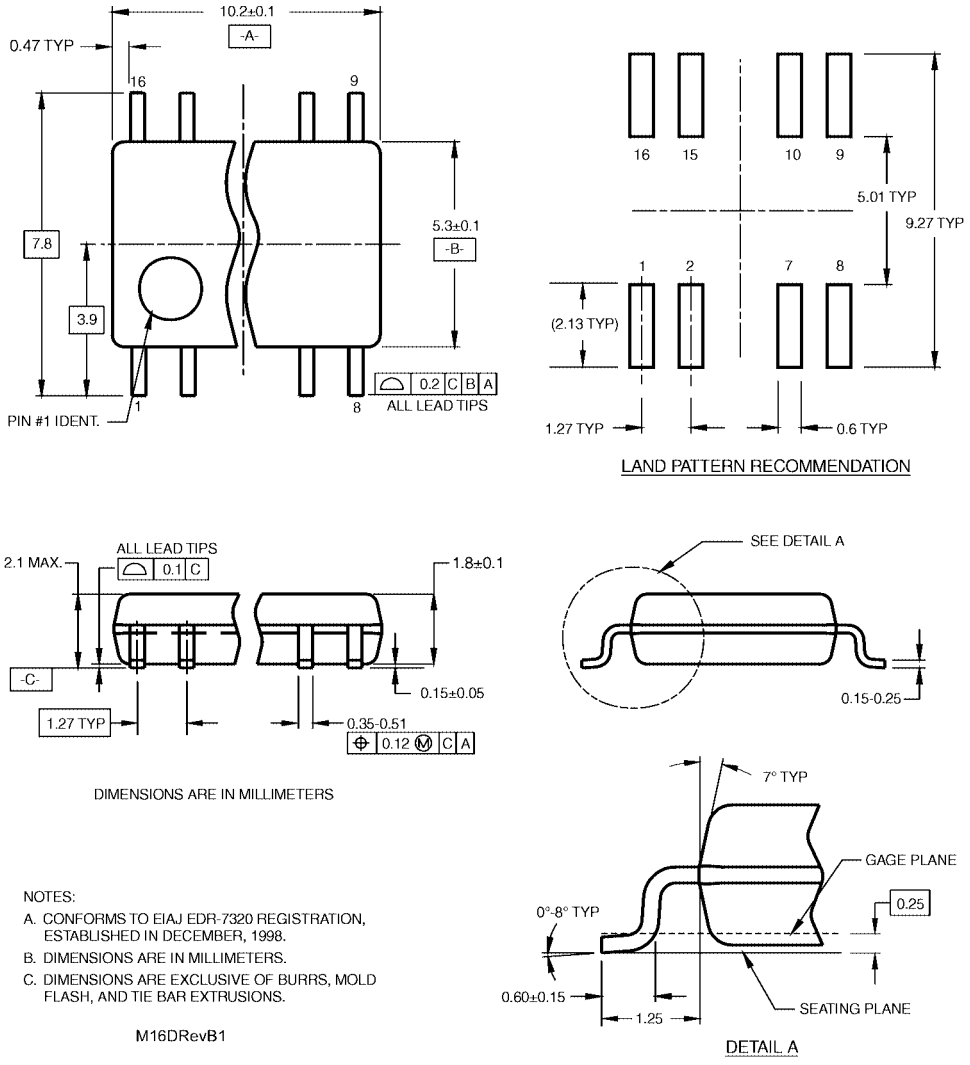
Note 7: C_{PD} determines the no load dynamic power consumption, $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$, and the no load dynamic current consumption, $I_S = C_{PD} V_{CC} f + I_{CC}$.

Physical Dimensions inches (millimeters) unless otherwise noted



16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
Package Number M16A

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



NOTES:

A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.

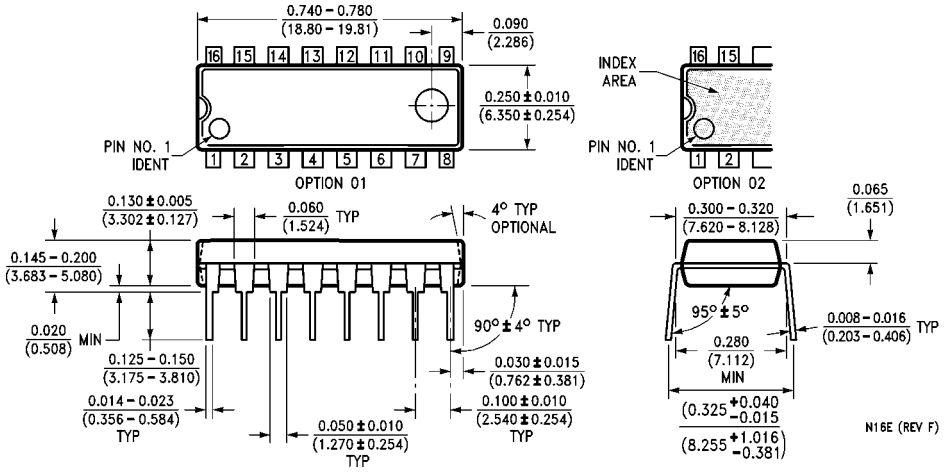
B. DIMENSIONS ARE IN MILLIMETERS.

C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

M16DRevB1

16-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
Package Number M16D

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



16-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide
Package Number N16E